

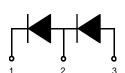
## Stealth™ Rectifier

## FFPF60SA60DS

#### **Features**

- Soft Recovery (t<sub>b</sub> / t<sub>a</sub> > 1.2)
   Fast Recovery (t<sub>rr</sub> < 25ns)</li>
- Reverse Voltage, 600V
- Forward Voltage (@  $T_C = 125^{\circ}C$ ), < 2.0 V
- Enhanced Avalanche Energy

# TO-220F-3L



Rev. A, October 2004

## **Applications**

- Switch Mode Power Supplies
- Hard Swithed PFC Boost Diode
- UPS Free wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

## Absolute Maximum Ratings (per leg) T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Peak Repetitive Reverse Voltage	600	V
$V_{RWM}$	Working Peak Reverse Voltage	600	V
V <sub>R</sub>	DC Blocking Voltage	600	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 95 °C	8	Α
I <sub>FSM</sub>	Non-repetitive Peak Surge Current 60Hz Single Half-Sine Wave	80	А
P <sub>D</sub>	Power Dissipation	26	W
W <sub>AVL</sub>	Avalanche Energy (1A, 40mH)	20	mJ
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature	- 65 to +150	°C

### **Thermal Characteristics**

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Maximum Thermal Resistance, Junction to Case	3.125	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	62.5	°C/W

Symbol	Parameter		Min.	Тур.	Max.	Units
V <sub>FM</sub> *	Maximum Instantaneous Forward Voltage $I_F = 8A$ $I_F = 8A$	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C	-	2.0 1.6	2.4 2.0	V
I <sub>RM</sub> *	Maximum Instantaneous Reverse Current @ rated V <sub>R</sub>	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C	-	- -	100 1000	μΑ
t <sub>rr</sub>	Maximum Reverse Recovery Time (I <sub>F</sub> =1A, di/dt = 100A/μs, V <sub>R</sub> = 30V)		-	-	25	ns
t <sub>rr</sub>	Maximum Reverse Recovery Time (I <sub>F</sub> =8A, di/dt = 100A/μs, V <sub>R</sub> = 30V)		-	-	30	ns
t <sub>rr</sub> I <sub>rr</sub> Q <sub>rr</sub>	Reverse Recovery Time Reverse Recovery Current Reverse Recovery Charge (I <sub>F</sub> =8A, di/dt = 200A/μs, V <sub>R</sub> = 390V)		- - -	39 2 39		ns A nC

<sup>\*</sup> Pulse Test: Pulse Width=300µs, Duty Cycle=2%

# **Typical Characteristics**

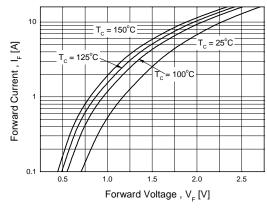


Figure 1. Typical Forward Voltage Drop vs. Forward Current

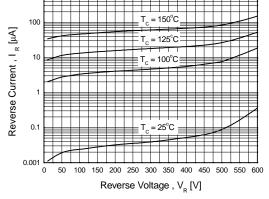


Figure 2. Typical Reverse Current vs. Reverse Voltage

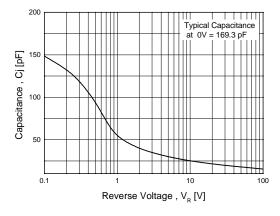


Figure 3. Typical Junction Capacitance

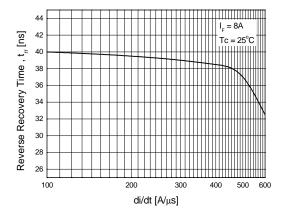


Figure 4. Typical Reverse Recovery Time vs. di/dt

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## **Typical Characteristics** (Continued)

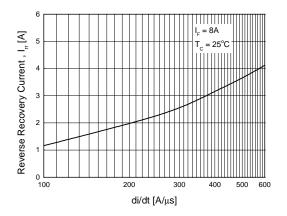


Figure 5. Typical Reverse Recovery Current vs. di/dt

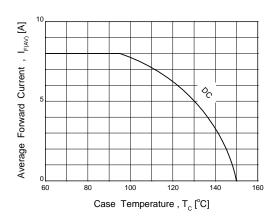


Figure 6. Forward Curent Derating Curve

## **Test Circuits and Waveforms**

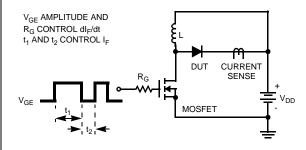


Figure 7. t<sub>rr</sub> Test Circuit

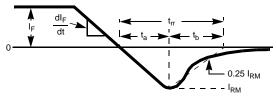


Figure 8.  $t_{rr}$  Waveforms and Definitions

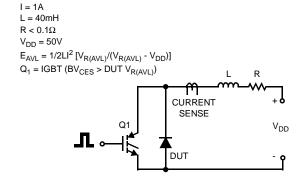


Figure 9. Avalanche Energy Test Circuit

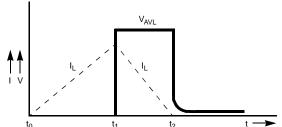
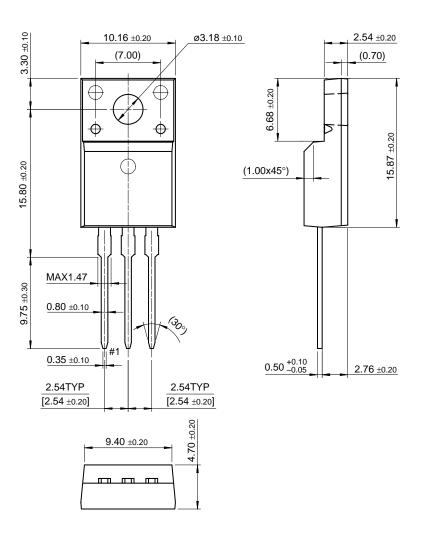


Figure 10. Avalanche Current and Voltage Waveforms

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# **Package Dimensions**

# TO-220F



Dimensions in Millimeters

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CROSSVOLT™	GlobalOptoisolator™	MicroPak™	QFET <sup>®</sup>	SuperSOT™-8
DOME™	GTO™	MICROWIRE™	QS™	SyncFET™
EcoSPARK™	HiSeC™	MSX™	QT Optoelectronics™	TinyLogic <sup>®</sup>
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EnSigna™	i-Lo™	OCX™	RapidConfigure™	TruTranslation™
FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
FACT Quiet Series™		OPTOLOGIC <sup>®</sup>	μSerDes™	UltraFET <sup>®</sup>
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Programmable Active Droop™		POP™	SPM™	

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